



LED570-66-60



TECHNICAL DATA

High Power LED Array, 60 chips

InGaAlP

LED570-66-60 is a wide viewing and extremely high output power illuminator assembled with a total of 60 high efficiency InGaAlP diode chips, mounted on a metal stem TO-66 with AlN ceramics and covered with double coated clear silicone and epoxy resin. These devices are designed for high current operation with proper heat sinking to improve thermal conductive efficiency.

Specifications

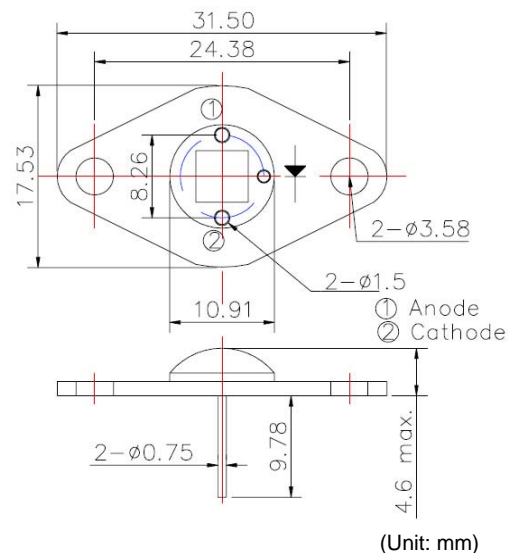
- Structure: InGaAlP, 60 LED chips
- Peak Wavelength: typ. 570 nm
- Optical Output Power: typ. 36 mW
- Package: TO-66 stem with AlN, clear epoxy resin

Absolute Maximum Ratings (T_C=25°C)

Item	Symbol	Value	Unit
Power Dissipation	P _D	4.5	W
Forward Current	I _F	400	mA
Pulsed Forward Current * ¹	I _{FP}	600	mA
Reverse Voltage	V _R	50	V
Operating Temperature	T _{opr}	-30 ... +85	°C
Storage Temperature	T _{stg}	-30 ... +110	°C
Soldering Temperature * ²	T _{sol}	265	°C

*¹ duty = 1%, pulse width = 1 μs

*² must be completed within 3 seconds



(Unit: mm)



Electro-Optical Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Total Radiated Power	P _O	I _F = 240 mA	-	36	-	mW
Brightness	I _V	I _F = 240 mA	-	7.0	-	cd
Forward Voltage	V _F	I _F = 240 mA	-	11.0	-	V
Reverse Voltage	V _R	I _R = 10 μA	50	-	-	V
Peak Wavelength	λ _P	I _F = 240 mA	560	570	580	nm
Half Width	Δλ	I _F = 240 mA	-	15	-	nm
Viewing Half Angle	Θ _{1/2}	I _F = 240 mA	-	±60	-	deg.

Heat Sink is required, thermal resistance <8K/W

Notes

- This high power LED must be cooled!
- Do not view directly into the emitting area of the LED during operation!
- The above specifications are for reference purpose only and subjected to change without prior notice.



NOTE
LED
MUST BE COOLED